MAX1879EUA Rev. A

RELIABILITY REPORT

FOR

MAX1879EUA

PLASTIC ENCAPSULATED DEVICES

February 14, 2003

MAXIM INTEGRATED PRODUCTS

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Conclusion

The MAX1879 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX1879 single-cell lithium-ion (Li+) battery charger utilizes an efficient pulse-charging architecture to minimize power dissipation in portable devices. This architecture combines the efficiency of switch-mode chargers with the simplicity and low cost of linear chargers. This simple device, in conjunction with a current-limited wall cube and a PMOS transistor, allows safe and fast charging of a single Li+ cell.

The MAX1879 initiates charging in one of three ways: battery insertion, charger power-up, or toggling the THERM pin. Key safety features include continuous voltage and temperature monitoring, a preset charger time-out, and an 8mA precharge current mode to charge near-dead cells. Automatic detection of input power removal shuts down the device, minimizing current drain from the battery. An overall system accuracy of 0.75% ensures that the cell capacity is fully utilized without cycle life degradation.

The MAX1879 is offered in a space-saving 8-pin μ MAX package. An evaluation kit (MAX1879EVKIT) is available to help reduce design time.

B. Absolute Maximum Ratings Item	Rating
IN, CHG, GATE to GND	-0.3V to +26V
BATT, TSEL, THERM, ADJ to GND	-0.3V to +6V
GATE to IN	-6V to +0.3V
THERM, ADJ to BATT	-6V to +0.3V
GATE Continuous Current	-10mA
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70°C)	
8-Pin μMAX	330mW
Derates above +70°C	
8-Pin μMAX	4.1mW/°C

II. Manufacturing Information

A. Package]	vpe:	8-Pin uMAX
III. Packaging Information		
F. Date of Ini	tial Production:	April, 2001
E. Assembly	Location:	Malaysia, Philippines or Thailand
D. Fabrication	n Location:	California, USA
C. Number of	Device Transistors:	482
B. Process:		B12 (Standard 1.2 micron silicon gate CMOS)
A. Descriptio	n/Function:	Simple, Efficient, 1-Cell Li+ Pulse Charger

A. Package Type:	8-Pin uMAX
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	# 05-2301-0090
H. Flammability Rating:	Class UL94-V0

I. Classification of Moisture Sensitivity per JEDEC standard JESD22-112: Level 1

IV. Die Information

A. Dimensions:	61 x 84mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

Α.	Quality Assurance Contacts:	Jim Pedicord (Manager, Reliability Operations)
		Bryan Preeshl (Executive Director)
		Kenneth Huening (Vice President)

- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

 $\lambda = \underbrace{1}_{\text{MTTF}} = \underbrace{\frac{1.83}{192 \times 4389 \times 78 \times 2}}_{\text{Temperature Acceleration factor assuming an activation energy of 0.8eV}$

 $\lambda = 13.92 \times 10^{-9}$

 λ = 13.92 F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-5414) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The PY68 die type has been found to have all pins able to withstand a transient pulse of ± 1000 V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ± 50 mA.

Table 1 Reliability Evaluation Test Results

MAX1879EUA

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test	t (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		78	0
Moisture Testi	ng (Note 2)				
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	uMAX	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Str	ress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots. Note 2: Generic Package/Process data

Attachment #1

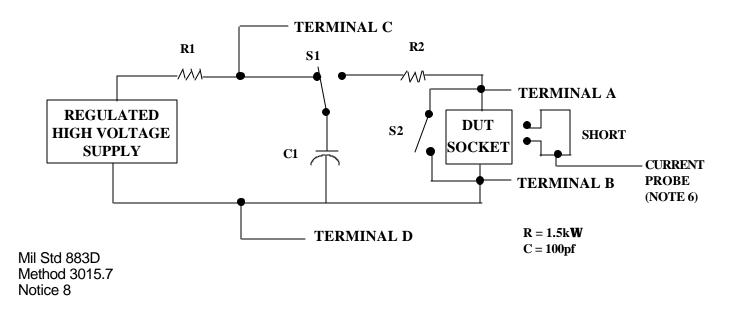
	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V _{PS1} <u>3/</u>	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

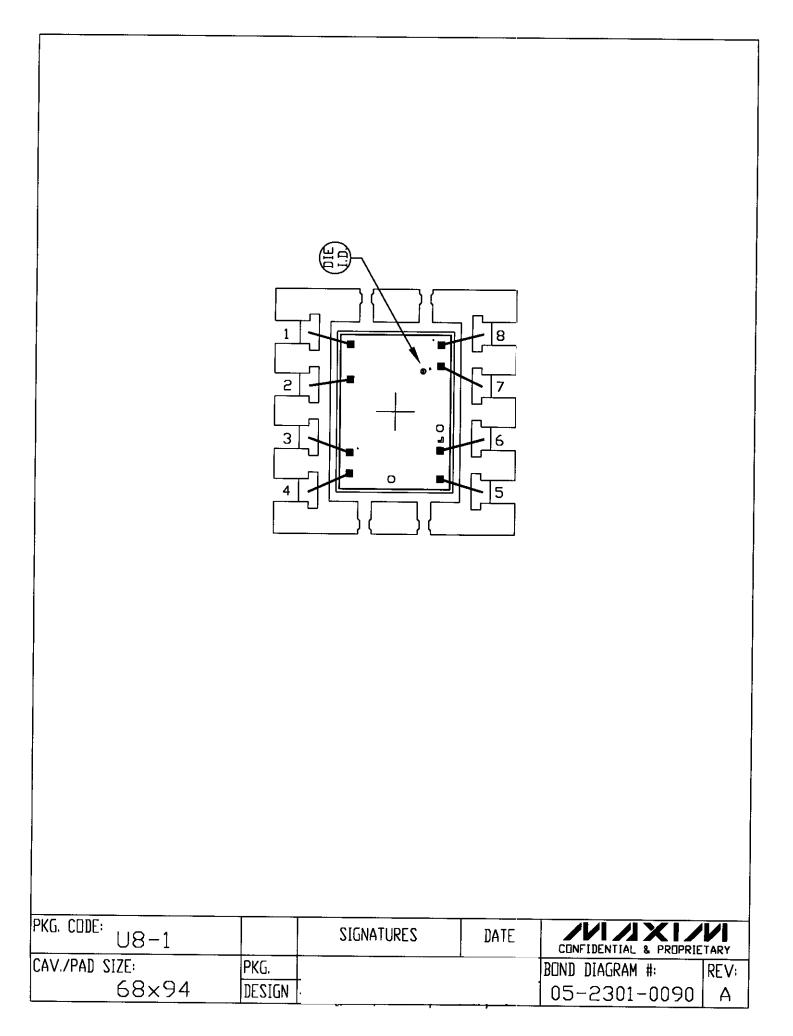
TABLE II. Pin combination to be tested. 1/2/

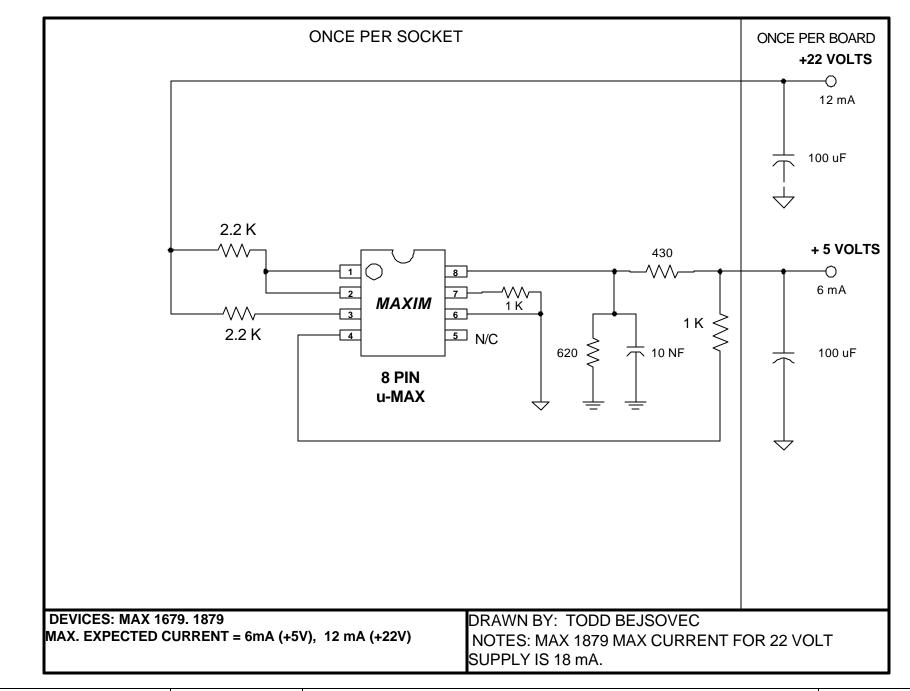
- 1/ Table II is restated in narrative form in 3.4 below.
- $\overline{2/}$ No connects are not to be tested.
- $\overline{3/}$ Repeat pin combination I for each named Power supply and for ground

(e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS} , V_{BB} , GND, + V_{S} , - V_{S} , V_{REF} , etc).

- 3.4 <u>Pin combinations to be tested.</u>
 - a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
 - b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
 - c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.







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